Rev. A1

SMB1N-800D

- High Power LED
- 800 nm, 450 mW
- SMD package, PA9T

• Dimension: 5.0 x 5.2 x 1.0 mm

• Viewing Angle: 136°





Description

SMB1N-800D is a surface mount AlGaAs High Power LED with a typical peak wavelength of **800 nm** and radiation of **450 mW**. It comes in SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and molded with silicone resin.

Maximum Ratings (TCASE=25°C)

B	O. make al	Val	1126		
Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	P_D		2100	mW	
Forward Current	IF		800	mA	
Pulse Forward Current *1	I _{FP}		2000	mA	
Reverse Voltage	V _R		5	V	
Thermal Resistance	RTHJA		10	K/W	
Junction Temperature	T_J		120	°C	
Operating Temperature	T_{CASE}	- 40	+ 100	°C	
Storage Temperature	T _{STG}	- 40	+ 100	°C	
Lead Solder Temperature *2	T_{SLD}		+ 250	°C	

^{*1} duty=1%, pulse width = 10 µs

Electro-Optical Characteristics (TCASE=25°C)

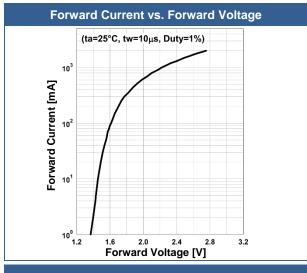
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	λ_P	I _F =500mA	790		810	nm
Half Width	$\Delta \lambda$	I _F =500mA		32		nm
Forward Voltage	VF	I _F =800mA		2.1	2.6	V
Forward Voltage	V_{FP}	I _{FP} =2A		2.8		V
Radiated Power *1	Po	I _F =800mA	350	450		mW
Radiated Fower	FO	I _{FP} =2A 10	1000		IIIVV	
Dadient Intensity *2	le	I _F =800mA		150		mW/sr
Radiant Intensity *2		I _{FP} =2A		330		IIIVV/SI
Viewing Angle	φ	I _F =100mA		128		deg.
Rise Time	t_R	I _F =800mA		20		ns
Fall Time	t⊧	I _F =800mA		30		ns

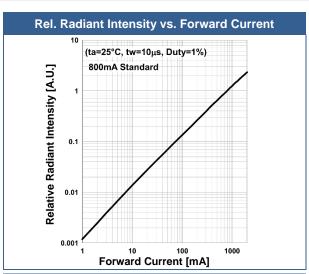
^{*1} measured by S3584-08

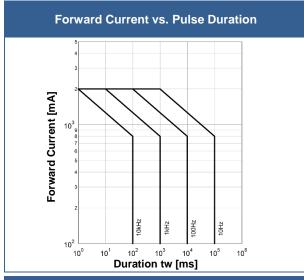
^{*2} must be completed within 5 seconds

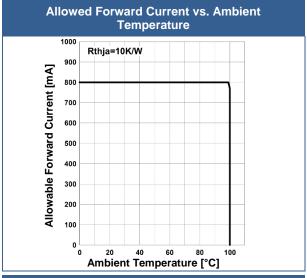
^{*2} measured by CIE127-2007 Condition B

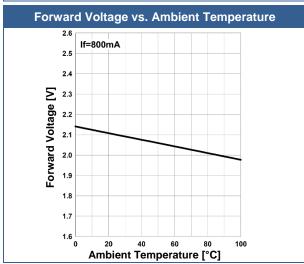
Typical Performance Curves

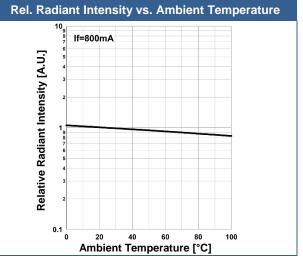










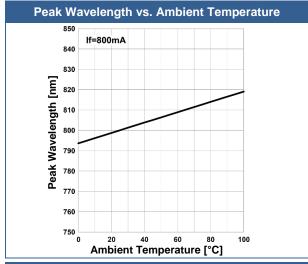


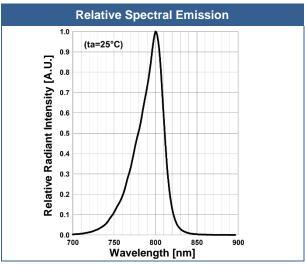


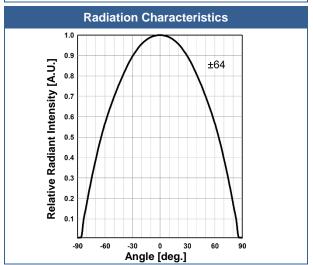
ROITHNER LASERTECHNIK GmbH

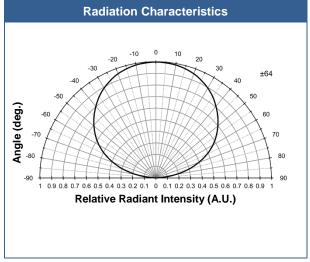
WIEDNER HAUPTSTRASSE 76 IO40 VIENNA AUSTRIA TEL. +43 I 586 52 43 -0, FAX. -44 OFFICE@ROITHNER-LASER.COM



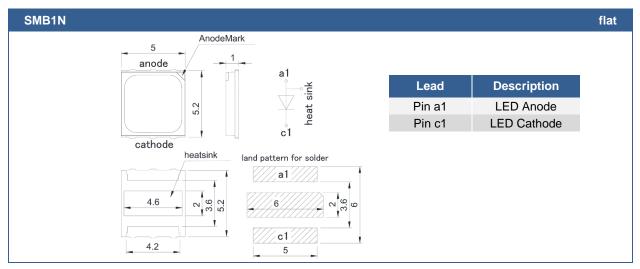








Outline Dimensions



All Dimensions in mm

Precautions

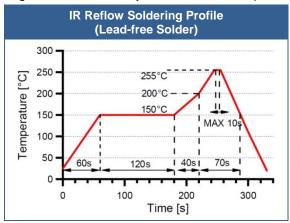
Soldering:

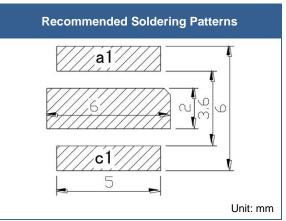
- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

Recommended soldering conditions:

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.





Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

Cleaning:

Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS

DO NOT USE ultrasonic cleaners

Static Electricity:

LEDs are sensitive to electrostatic discharge (ESD). Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

Radiation:

During operation these LEDs do emit **high intensity light**, which is hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. **Protective glasses are recommended**. It is further advised to attach a warning label on products/systems.

Operation:

Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device. Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

Revisions History

Rel.	Rel. Date	Chapter	Modification	Page
A1	2020-10-03	-	Initial release	-

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The above specifications are for reference purpose only and subjected to change without prior notice